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Amend
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.	10/066,023	Confirmation No.	4878
First Inventor	Allen K. Lam	Filing Date	01/30/02
Tech. Center/ Art Unit	2826	Examiner	Alexander O. Williams
Title:	Package For Semiconductor Die Containing Symmetrical Lead And Heat Sink		
Docket No.:	AAT009-2D US	Customer No.:	34036

Santa Clara, California
November 20, 2003

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

In response to Office Action dated June 20, 2003, please amend the above-identified application as follows.

An Amendment to the Title is set forth on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims, which begins on page 3 of this paper.

Remarks/Arguments begin on page 5 of this paper.

Appl. No. 10/066,023
Amdt dated November 20, 2003
Rply to Office Action of June 20, 2003

Amendment to the Title:

Please amend the title to read as follows:

C' "Package For Semiconductor Die Containing Symmetrical Lead And Heat Sink"

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